Fully-Automatic Vacuum Mounter

RAD-2512F/12

Outline

- Fully-automatic wafer mounter equipped with a pre-cut tape mounting function in a vacuum environment.
- By using our unique vacuum control method, wafer mounting is performed without any contact with wafer surface.
- By adopting the non-contact wafer backside handling method, contamination of wafer is prevented.

Options

- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
- Vision System (Wafer ID Reader & Barcode Attachment System)
- Dicing Tape In-line Pre-cutting

Suitable Tape

- Dicing tape: Adwill D series, G series

Facility

<table>
<thead>
<tr>
<th>Facility</th>
<th>Voltage</th>
<th>Frequency</th>
<th>Phase</th>
<th>Power consumption</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power Supply</td>
<td>AC200-230V ±10%</td>
<td>50/60Hz</td>
<td>single phase</td>
<td>4.0kW</td>
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<td>(AC190-253V)</td>
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<tr>
<td>Air Supply</td>
<td>0.6-0.8MPa</td>
<td>50/60Hz</td>
<td>single phase</td>
<td>&gt;800L/min (ANR)</td>
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<tr>
<td>Vacuum Supply</td>
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<tr>
<td>(for workpiece)</td>
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<tr>
<td>(for vacuum chamber)</td>
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<td>&gt;-80kPa</td>
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<td>&gt;1.0Pa</td>
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<td>&gt;250L/min</td>
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Applicable Wafer Size

200mm (*300mm capability as option)

Size

- Width: 2,203mm
- Depth: 3,092mm
- Height: 1,800mm

(excluding the signal tower and protruding parts)

Weight

2,600kg

UPH

40 wafers/hour

The above processing capacity is based on following conditions:

- Wafer: 200mm diameter non-polished mirror wafer
- Ring frame: for 200mm wafer
- Dicing tape: D-184 from LINTEC

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External View

Unit: mm

Contact:

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